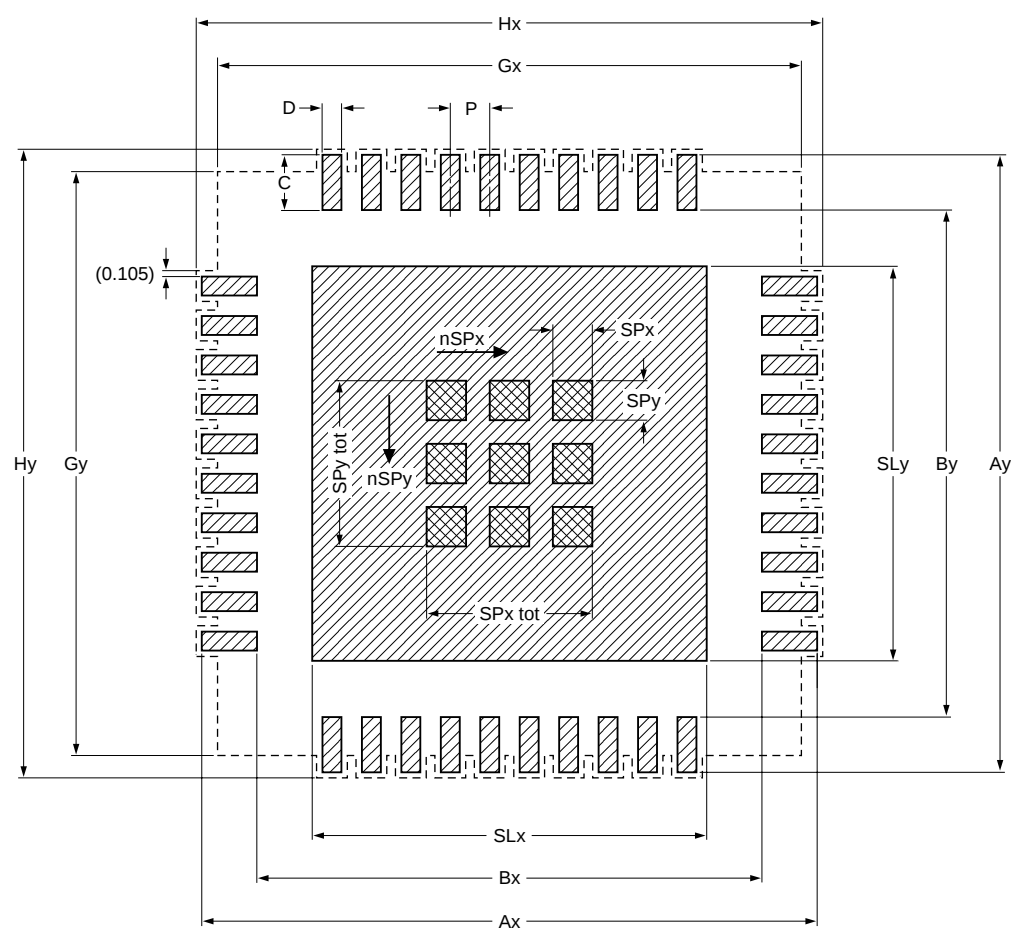


Footprint information for reflow soldering of HVQFN28 package

SOT788-1



Generic footprint pattern

Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

nSPx	nSPy
3	3

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.650	7.000	7.000	4.800	4.800	1.100	0.350	4.000	4.000	2.400	2.400	0.600	0.600	6.300	6.300	7.250	7.250